BIRLA INSTITUTE OF TECHNOLOGY AND SCIENCE, PILANI INSTRUCTION DIVISION

SECOND SEMESTER 2018-19

Course Handout (Part II)

Date: 07/01/2019

In addition to Part I (General Handout for all courses appended to the time table) this portion gives further specific details regarding the course.

Course No. : BITS F415

Course Title : Introduction to MEMS
Instructor-in-charge : Prof. Sanket Goel

Instructor : Prof. Sanket Goel and Dr. Satish Kumar Dubey

1. Scope and Objective of the Course:

The course introduces the basic concepts in MEMS (Micro Electromechanical Systems) with a view to address a class of students from science and engineering disciplines. The discussion on topics like MEMS design, Microfabrication, Microfluidics, Microrobotics and Microsensors have been structured in the course plan. The objective of the course is to equip the students from various aspects and with basic knowledge of the area of MEMS.

2. Text Book:

Tai-Ran Hsu, MEMS and Micro systems Design and Manufacture, Tata McGraw Hill, 2002

Reference Books:

- i. G.K. Ananthsuresh et al, 'Micro and Smart Systems', Wiley, India, 2010.
- ii. Nitaigour P. Mahalik, MEMS, Tata McGraw Hill, 2007
- iii. Marc Madou, Fundamentals of Microfabrication, CRC Press, 2002.
- iv. Chang Liu, Foundation of MEMS, Pearson Education Inc., NJ, 2006
- v. Nadim Maluf, Introduction to Microelectromechanical Systems Engineering, Artech House, 2000.
- vi. Stephen D. Senturia, Microsystem Design, Kluwer Academic Publishers, 2001
- vii. Gad- el-Hak, Introduction to MEMS, CRC Press, 2010.

3. Course Plan:

#	Learning Objectives	Торіс	Lectures	Chap. Sec.
1	Introduction – history, interventions, career opportu	2	Ch. 1(T), Ref (b)	
2	To understand MEMS fundamentals and components	Basic Concepts of MEMS Design and Fabrication	1	Ch. 3 Ref (a)
3	To understand basic MEMS governing laws	Scaling Laws – geometry, various forces, fluid mechanics etc	2	Ch. 9(T)
4	To understand Microsensors & Microactuatars	Microsensors & Microactuatars: working principles, design, applications	4	Ch. 2, (T)
5	To understand MEMS fabrication processes	Microfabrication Processes I lithography	3	Ch. 7 (T), Ch.7 Ref. (a)
6	To understand MEMS fabrication processes	Microfabrication Processes II soft-lithography, 3D printing	4	Ch. 3(T), Ch 8 7Ref. (a)
7	To understand how MEMS	Micromanufacturing – fundamental	3	C8h. 3 (T) Ch. 9

	can be harnessed for micromanufactering	design principles, MEMS integration, applications		Re9f. (a)	
8	To understand COMSOL based MEMS modelling	Modeling in MEMS – COMSOL fundamentals, design principles, examples	4	Ch. 4, 5, 6 (T)	
9	To understand meteorological applications for MEMS	Meteorology in MEMS – fundamentals of Meteorology, need for MEMS, recent applications	1	Class-notes	
10	To understand electronics components in MEMS	Electronics in MEMS – integration of IC, embedded systems with MEMS devices, with few design principles and examples	2	Chapter 7 (T)	
11	To RF components in MEMS	RF MEMS – Components, Biasing, Packaging, Microfabrication, Reliability, Applications	2	Ch.8 Ref (b), Class notes	
12	To RF components in MEMS	Optical MEMS – need for optical MEMS, Components, Biasing, Integrated optics, Reliability, Applications	1	Ch.7 Ref (b), Class notes	
13	To understand Microfluidics	Microfluidics – fundamentals, design parameters, fabrication aspects, characterization, applications	4	Ch. 5 Ref (a), Class Notes	
14	To understand Microsystem design considerations	Microsystem design – integration constraints, industrial applications, troubleshooting	2	Ch.10 Ref. (a)	
15	To understand MEMS packaging	MEMS Packaging – function of packaging, requirements, integration aspects, advantages, applications	Self study	Ch. 11 Ref (a)	
16	Lab sessions		5		
		Total	40		

4. Evaluation Scheme:

		Weightage			
Component	Duration	%	Marks	Date &Time	Remarks
Midterm	1Hr30m	20	60	11/3 9.00 - 10.30AM	Closed Book
Comprehensive Exam	3 Hr.	40	120	01/05 FN	Closed Book
Quizzes		15	45	During Lecture / Tutorial	Closed Book
Lab		10	30		Open Book
Project		15	45	To be announced	Open Book
Total		100	300		

5. Lab Experiments

- i. Introduction to the software COMSOL and its application in MEMS
- ii. Simulation of MEMS Actuators using COMSOL
- iii. Simulation of MEMS Sensors using COMSOL
- iv. Microfluidic simulations using COMSOL: Laminar Flow; Convection diffusion; Conjugate heat transfer
- v. Development of Micro-device using FDM based 3D printer.
- vi. Study the customized filament making for FDM 3D printer

- vii. Development of Micro-device with the photolithography process using dry film photoresist
- viii. Development of Micro-device using poly-di-methyl-siloxane (PDMS) based Soft-lithography
- ix. Development of paper Micro-device using solid wax printer
- x. Development of paper / polymer Micro-device using Xurography
- 6. **Chamber Consultation Hour:** To be announced in the class.
- 7. **Make-up Policy:** There will no make-ups unless for genuine reasons. Prior Permission of the Instructor-in-Charge is required to take a make-up for any component.
- 8. Notices: EEE/MechE Notice Board and CMS
- **9. Academic Honesty and Integrity Policy:** Academic honesty and integrity are to be maintained by all students throughout the semester, non-compliance of which will not be acceptable.

Instructor-In-Charge

BITS F415